

In-line Sputter System



Configurations en benefits

- Flexible substrate size up to 1100 x 1300 mm² (glass).
- Excellent thin-film uniformity of less than $\pm 5\%$.
- High Deposition Rate > 250 nm/m efficiency cathode.
- Sputter power: RF SkW, DC or pulsed DC max 20 kW.
- Mass flow controllers with highly uniform gas distribution.
- Substrate heating up to 400°C wit stable temperature control.
- Vertical or horizontal sputtering.

Options

- Carrier return system.
- Robot for auto loading.
- Integrated with Load-Lock, Robot arm, Glove box.
- Combined with Ion-source, Thermal source, E-beam, etc.
- RF or DC bias switching.
- Substrate RF plasma cleaning.
- Extra spare port for OES, RGA or extra process monitoring.

Applications

- Optoelectronic material (LED/Laser Diode).
- Communication device.
- Semiconductor device.

